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Thank you for your participation in the iNEMI Halogen Flame Retardant (HFR)-Free Leadership Call on January 20, 2009. Our records show that the following people participated in the first call.

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Most of you have not responded as to whether your firm will continue with the next round of discussions and which of the two proposed subprojects you and your firm's wish to participate in:

- Signal Integrity Initiative
- PCB Material Development Initiative

After reviewing schedules we have decided to hold our next meeting as a face-to-face meeting in Cupertino, CA on February 18, 2009 from 8:30 a.m. until 5 p.m. This schedule will allow time to have a group discussion followed by meetings of the two subprojects and a wrap up session. Further details will be provided shortly. Teleconference connections will be provided for those in Asia.

The second face to face meeting will be held at APEX in Las Vegas, NV on Wednesday, April 1, 2009 from 1:30 – 5:00 p.m.

The following link is where we will continue to post information.
http://www.inemi.org/cms/calendar/HFR-Free_Leadership.html

iNEMI HFR-free Leadership Phone Call – Minutes / Key Takeaways

1. Attendance: 25 companies with approximately 45 people on the call.
2. Jim McElroy indicated he would like to have discussions with non-member companies and can offer special discounts for this program to eliminate membership costs as a barrier.
3. Majority of questions centered around what was different about this effort vs. existing iNEMI projects. Answer was that existing projects are characterizing existing materials and looking at specific design points. They are not looking at in depth electrical characterization for various busses or looking at any specific technology envelope information. This new project is defining the attributes that all “acceptable” materials must have. This new effort will make full use of existing data.
4. IBM wanted to know where the demand for these HF Materials was coming from.
5. Cost of these new materials was raised as a big concern by many of the attendees.
6. A number of companies like the idea of moving system failures to material properties.
7. Hitachi noted that there cannot be a drop in for FR-4, the lead free transition has changed what classic FR-4 properties are. They believe the FR-4 spec is not really valid. Need to be clear on what we are calling FR-4. They asked the OEMs: If this new drop in material is developed but costs more, would they pay for it? No response from the OEMs on the call.
8. Various positions on CAF data noting both better and worse performance than FR-4.
9. Isola noted that it takes several years to make a new laminate and get UL approval. We can still develop the envelope and work towards getting this material fabricated/developed.
10. Next meeting is tentatively set for Feb 18 in Santa Clara area but checking into Feb 9th (IPC interim meetings in AZ).
11. A face-to-face meeting has been scheduled for IPC/APEX on Wednesday, April 1 from 1:30 – 5:00 p.m.
12. Attendees were asked to send contact information to Bob Pfahl and note which subteam (SI or PWB or both) that they would participate in.
13. Attendees have the responsibility to contact iNEMI to close on whether they will join or not, and identify who their technical contacts will be.